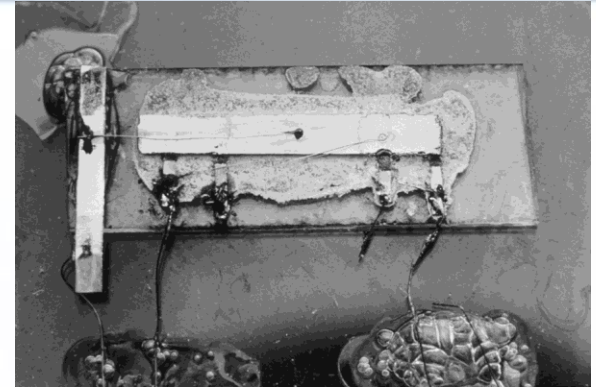


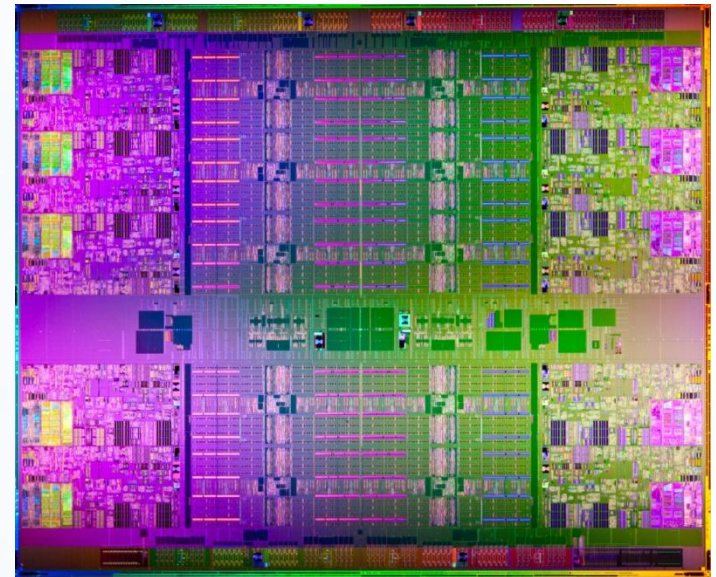
VLSI Trends

A Brief History

- ◆ **1958: First integrated circuit**
 - Flip-flop using two transistors
 - From Texas Instruments
- ◆ **2011**
 - **Intel 10 Core Xeon Westmere-EX**
 - ✓ 2.6 billion transistors
 - ✓ 32 nm process



Courtesy Texas Instruments



Courtesy Intel

Moore's Law

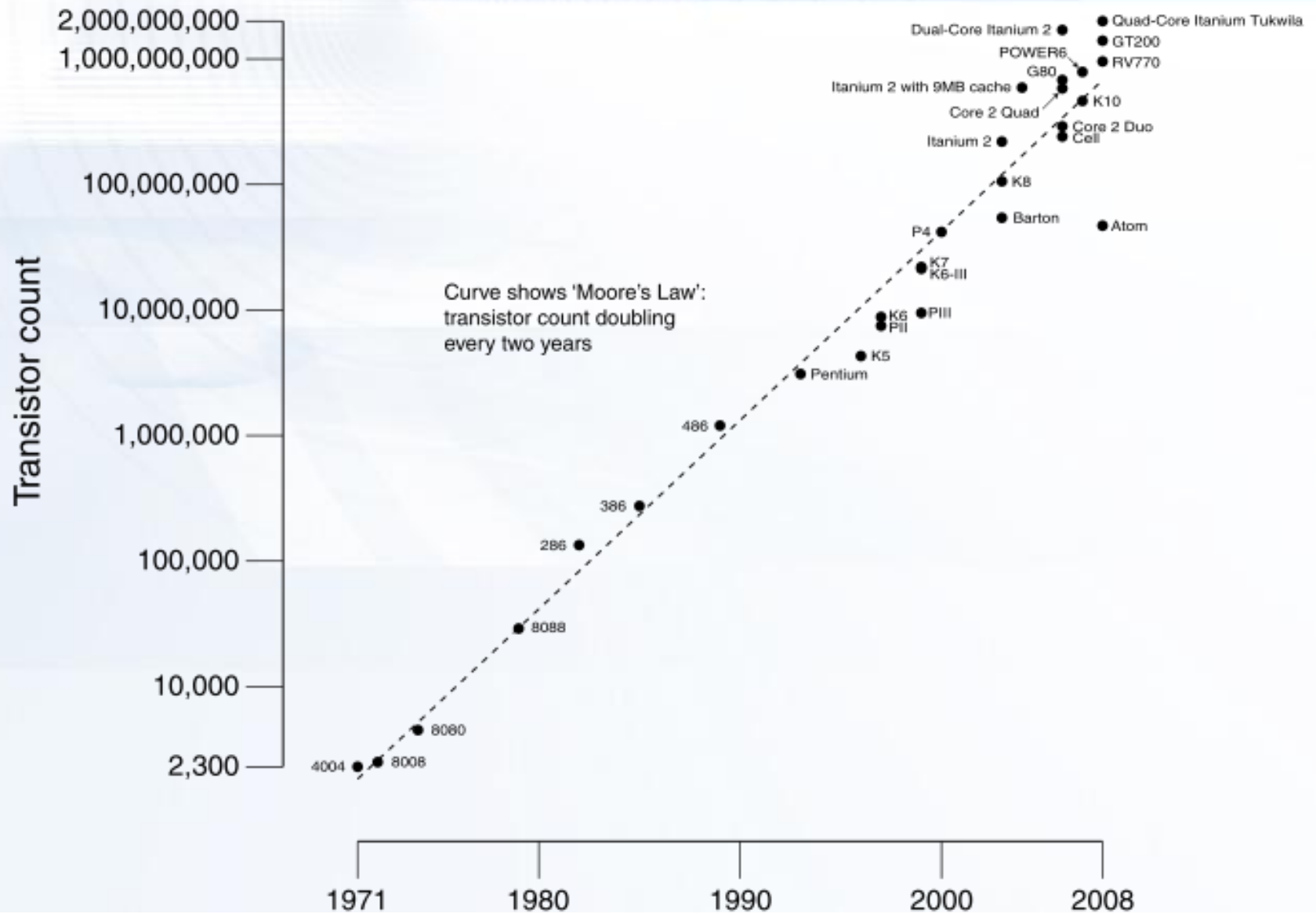
◆ Growth rate

- 2x transistors & clock speeds every 2 years over 50 years
- 10x every 6-7 years

◆ Dramatically more complex algorithms previously not feasible

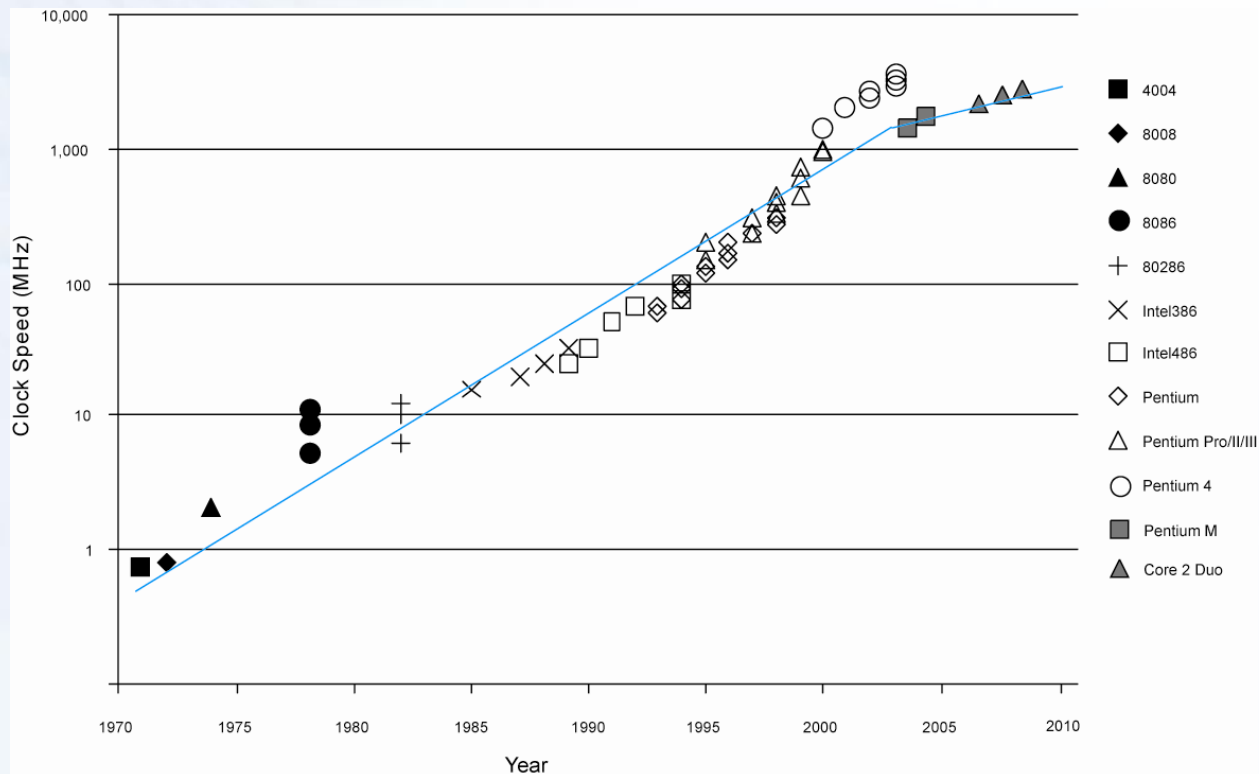
- Dramatically more realistic video games and graphics animation (e.g. Playstation 4, Xbox 360 Kinect, Nintendo Wii)
- 1 Mb/s DSL to 10 Mb/s Cable to 2.4 Gb/s Fiber to Homes
- 2G to 3G to 4G wireless communications
- MPEG-1 to MPEG-2 to MPEG-4 to H.264 video compression
- 480 x 270 (0.13 million pixels) NTSC to 1920x1080 (2 million pixels) HDTV resolution

Moore's Law

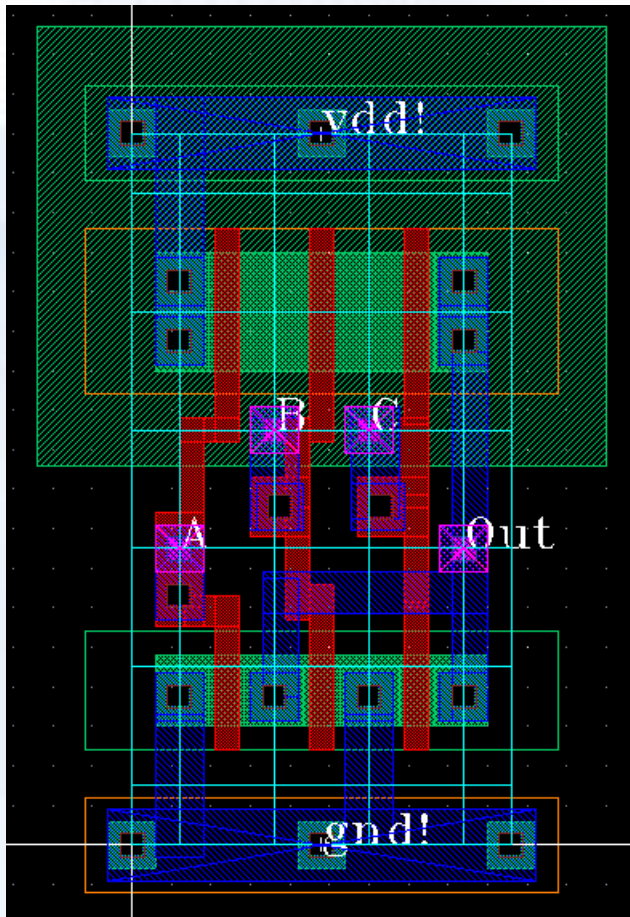


Moore's Law

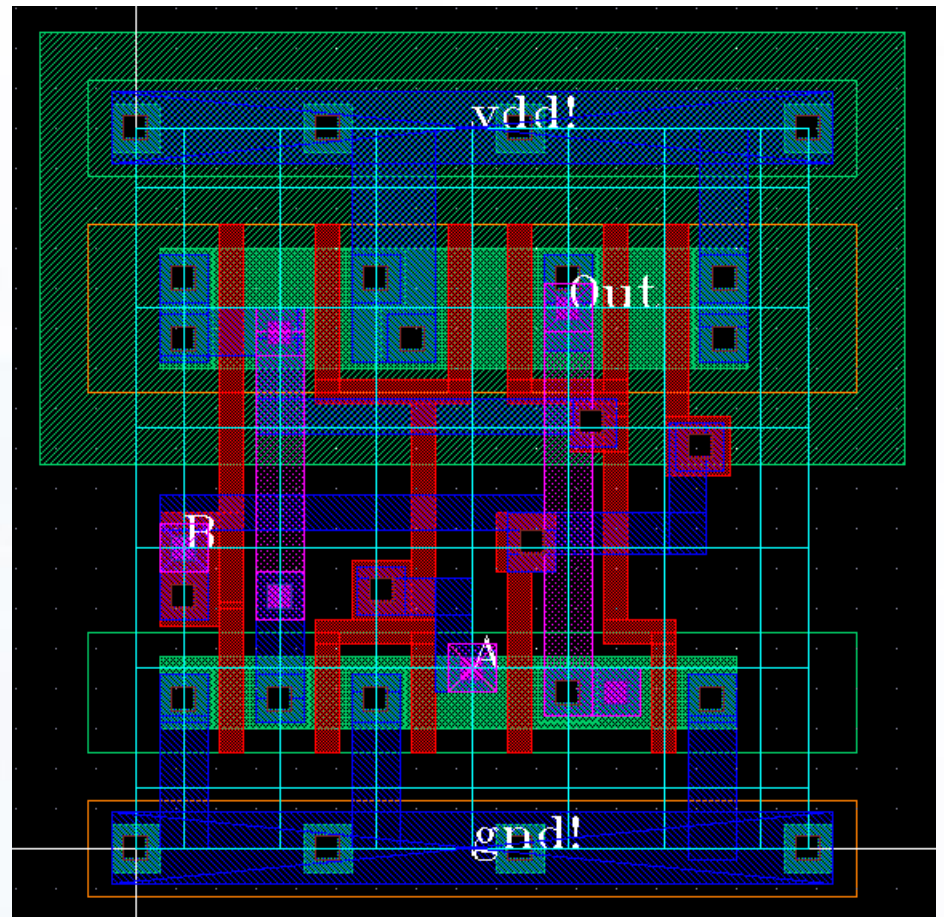
- ◆ Many other factors grow exponentially
 - Ex: clock frequency, processor performance



Standard Cells

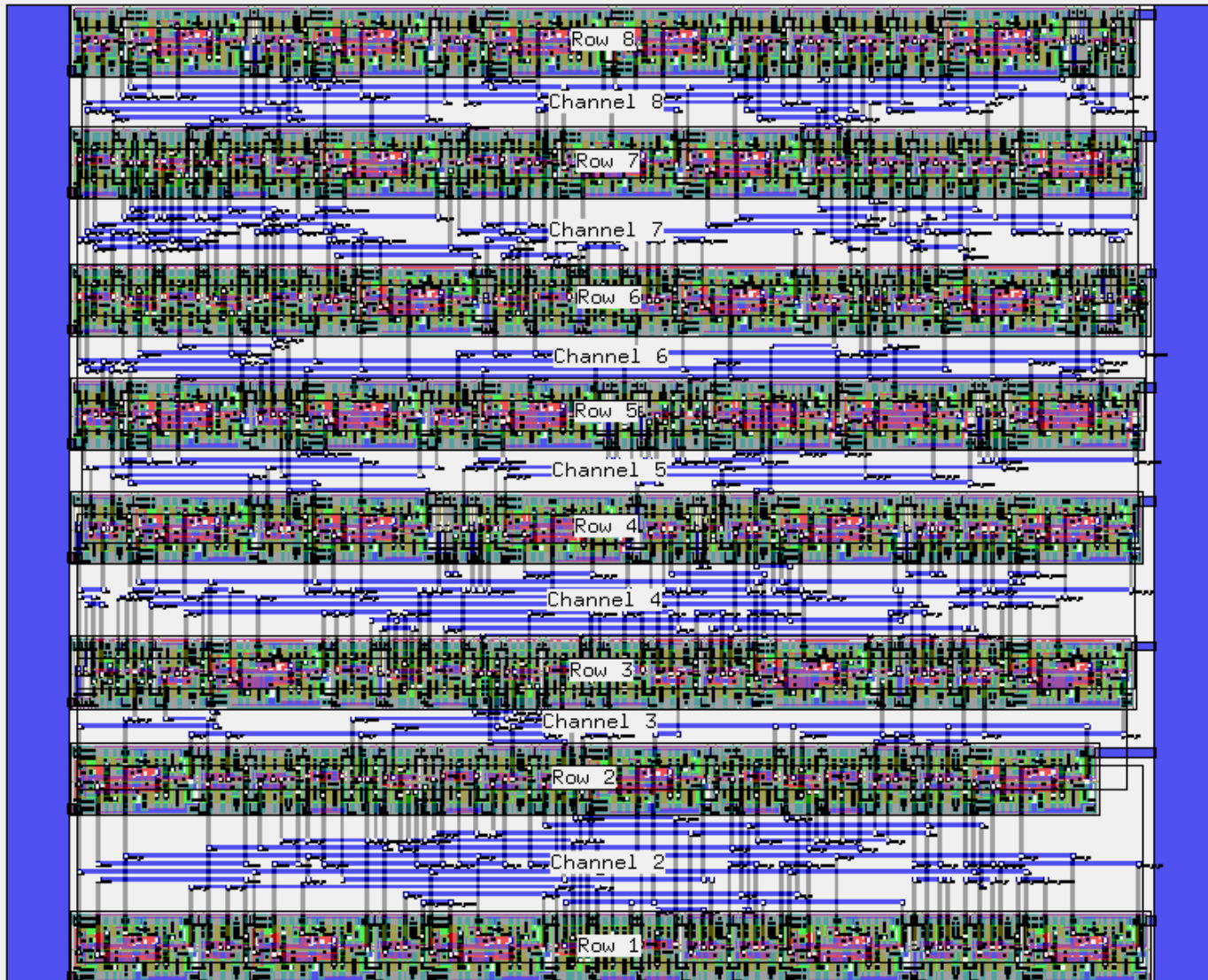


NOR-3



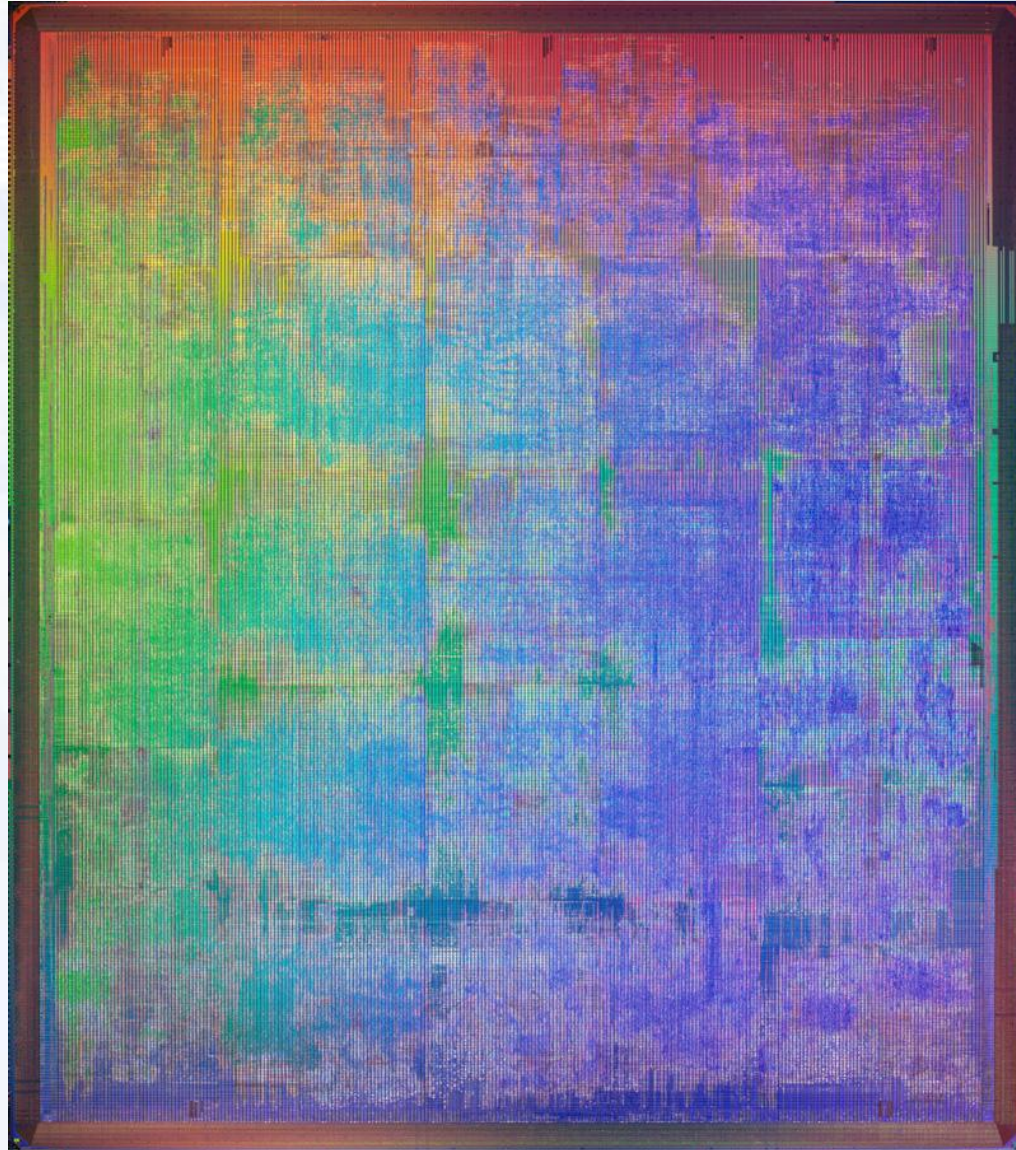
XOR-2

Standard Cell Layout

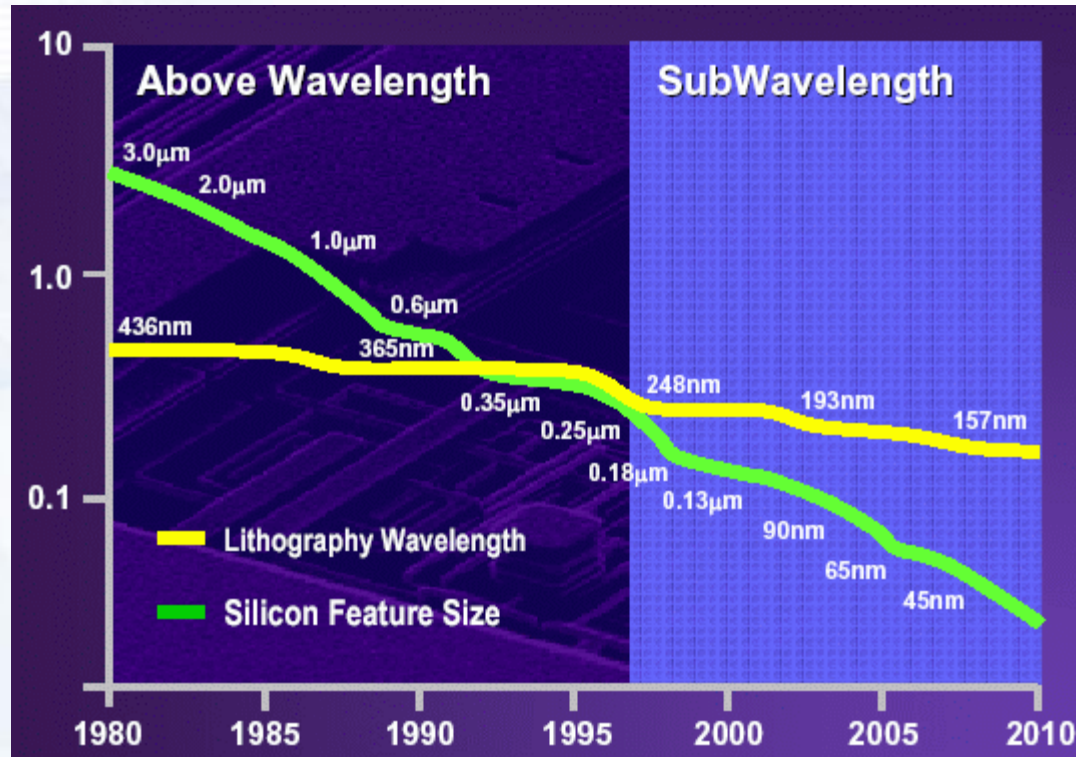


GeForce 8800

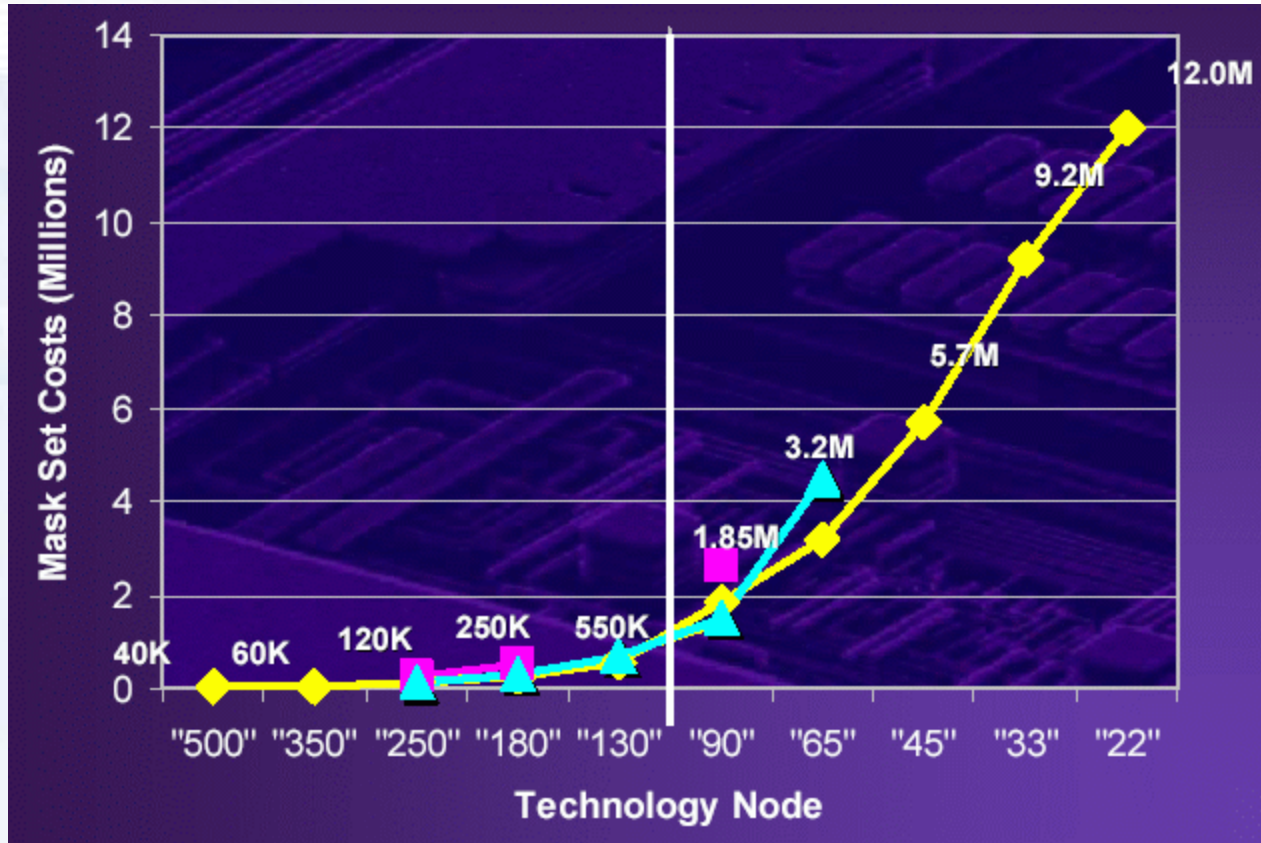
(600+ million transistors, about 60+ million gates)



Subwavelength Lithography Challenges



NRE Mask Costs



ASIC NRE Costs Not Justified for Many Applications

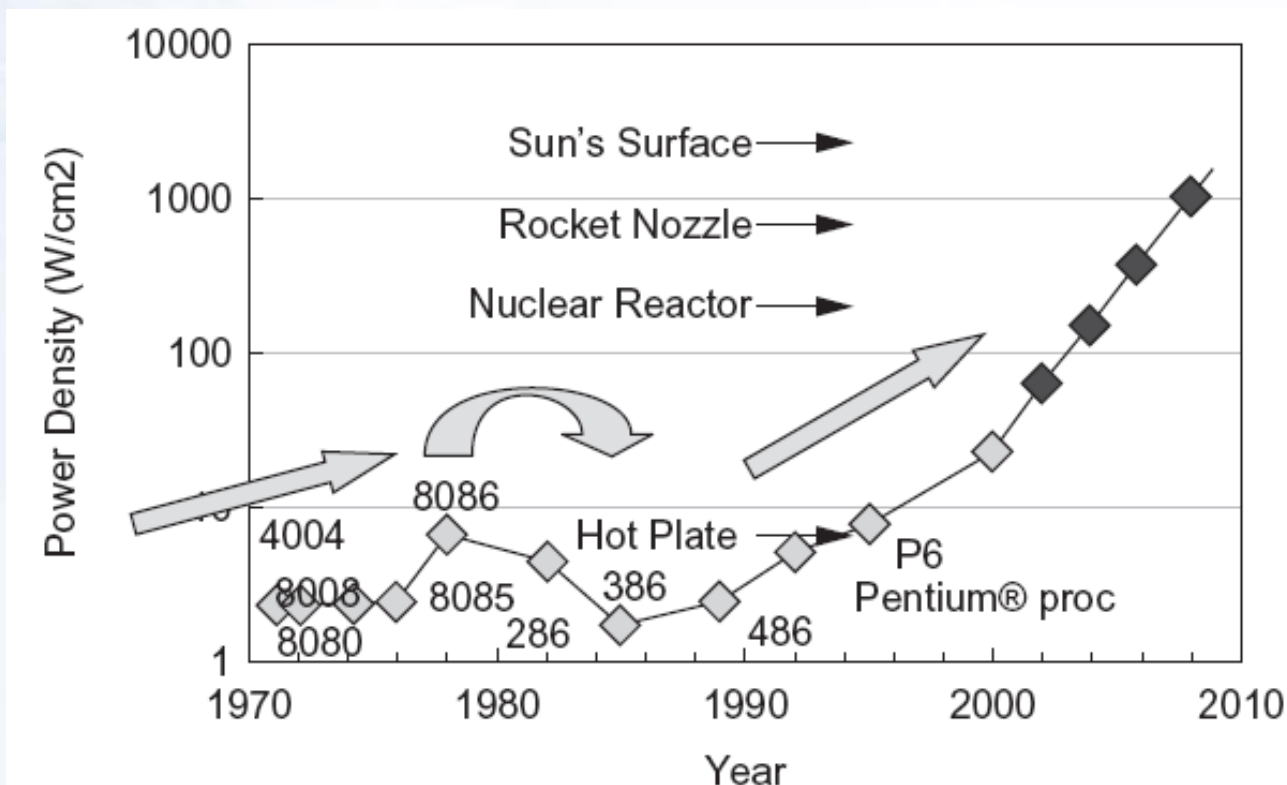
- ◆ **Forecast: By 2010, a complex ASIC will have an NRE Cost of over \$40M = \$28M (NRE Design Cost) + \$12M (NRE Mask Cost)**
- ◆ **Many “ASIC” applications will not have the volume to justify a \$40M NRE cost**
- ◆ **e.g. a \$30 IC with a 33% margin would require sales of 4M units (x \$10 profit/IC) just to recoup \$40M NRE Cost**

Power Density a Key Issue

- ◆ Motivated mainly by power limits
- ◆ $P_{\text{total}} = P_{\text{dynamic}} + P_{\text{leakage}}$
- ◆ $P_{\text{dynamic}} = \frac{1}{2} \alpha C V_{\text{DD}}^2 f$
- ◆ Problem: power (heat dissipation) density has been growing exponentially because clock frequency (f) and transistor count have been doubling every 2 years

Power Density a Key Issue

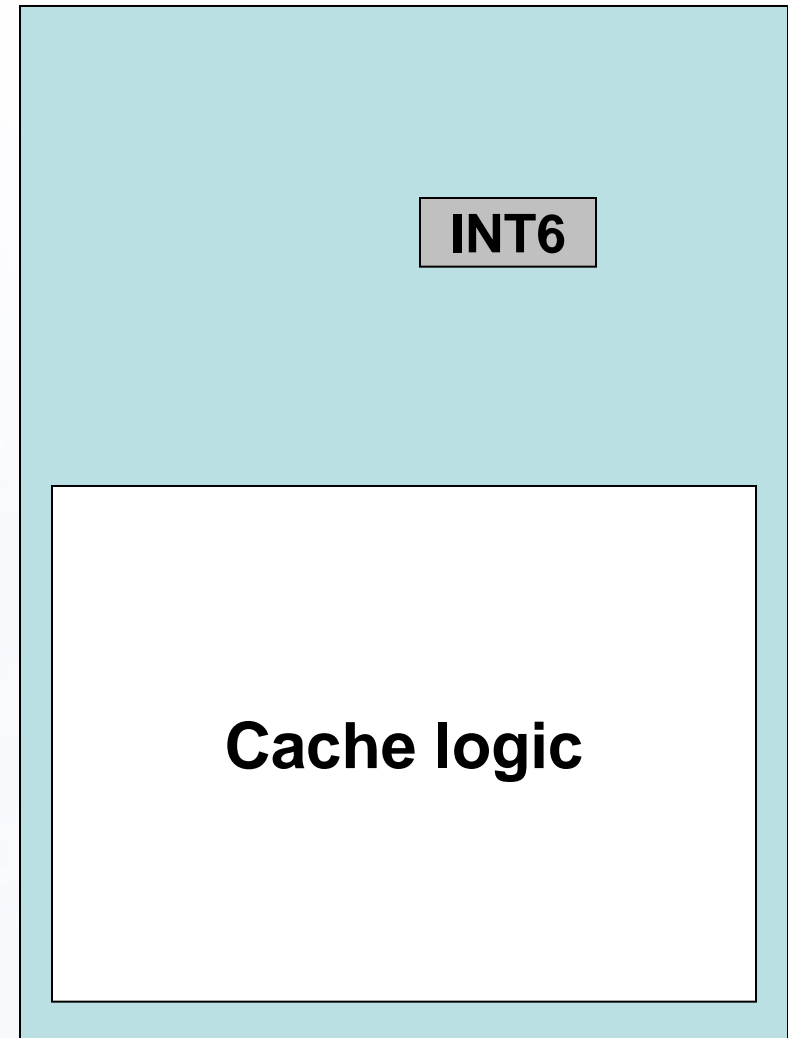
- ◆ Intel VP Patrick Gelsinger (ISSCC 2001)
 - “If scaling continues at present pace, by 2005, high speed processors would have power density of nuclear reactor, by 2010, a rocket nozzle, and by 2015, surface of sun.”



Courtesy Intel

Before Multicore Processors

- ◆ e.g. Intel Itanium II
 - 6-Way Integer Unit < 2% die area
 - Cache logic > 50% die area
- ◆ Most of chip there to keep these 6 Integer Units at “peak” rate
- ◆ Main issue is external DRAM latency (50ns) to internal clock (0.25ns) is 200:1
- ◆ Increase performance by higher clock frequency and more complex pipelining & speculative execution



Multicore Era

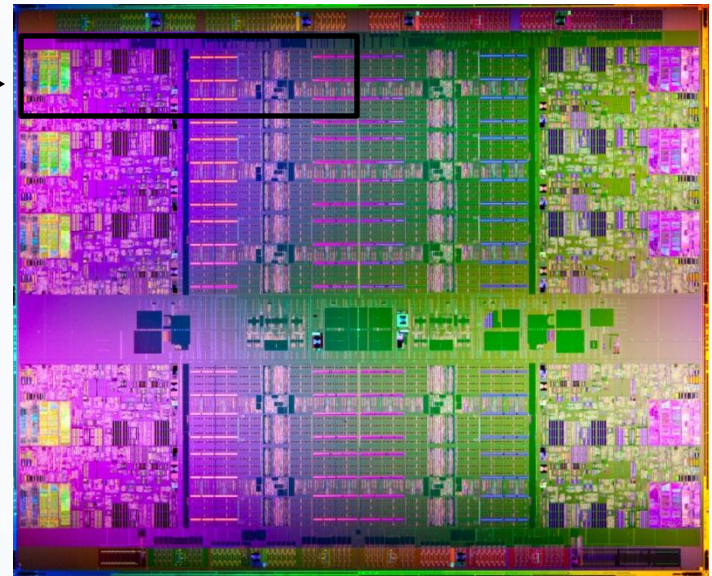
◆ Multicore era

- Operate at lower voltage and lower clock frequency
- Simpler processor cores
- Increase performance by more cores per chip

◆ e.g. Intel 10 Core Xeon Westmere-EX

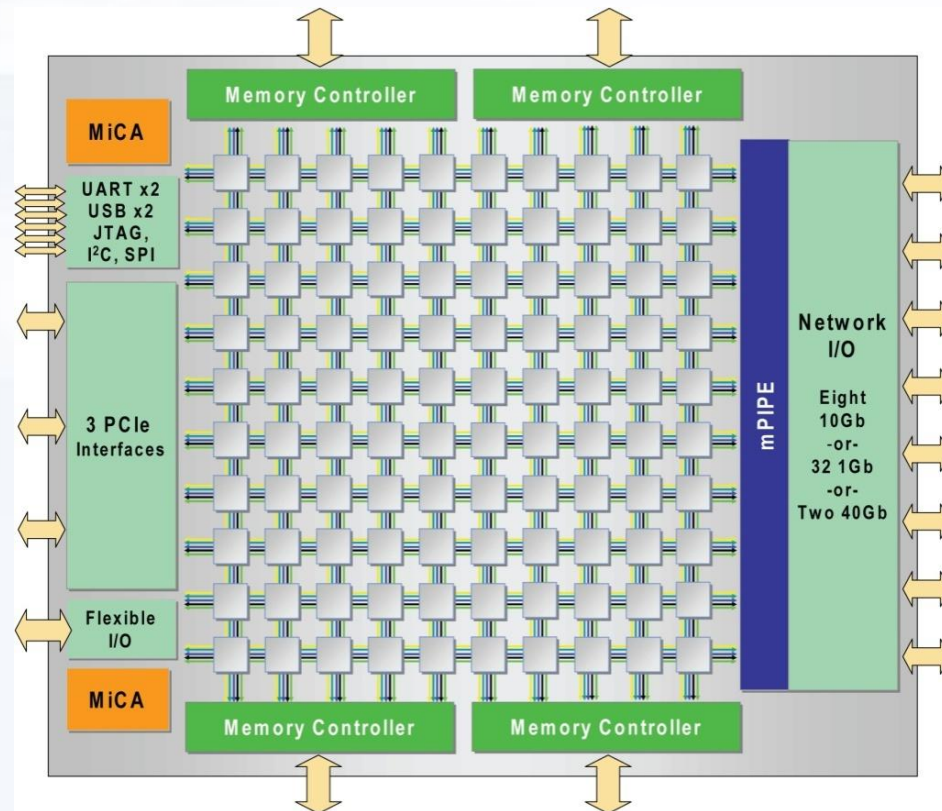
- 1.73-2.66 GHz (vs. previous Xeons at 4 GHz)

1 core →



Embedded Multicore Processors

- ◆ Embedded multicore processors replacing ASICs
 - Much simpler processor cores, much smaller caches
- ◆ e.g. Tiler-GX: 100 processors



What Does the Future Look Like?

Corollary of Moore's law: Number of cores will double every 18 months

	'02	'05	'08	'11	'14
Research	16	64	256	1024	4096
Industry	4	16	64	256	1024

(Cores minimally big enough to run a self-respecting OS!)

ITRS Roadmap

- ◆ Semiconductor Industry Association forecast
 - Intl. Technology Roadmap for Semiconductors

Year	2009	2012	2015	2018	2021
Feature size (nm)	34	24	17	12	8.4
L_{gate} (nm)	20	14	10	7	5
V_{DD} (V)	1.0	0.9	0.8	0.7	0.65
Billions of transistors/die	1.5	3.1	6.2	12.4	24.7
Wiring levels	12	12	13	14	15
Maximum power (W)	198	198	198	198	198
DRAM capacity (Gb)	2	4	8	16	32
Flash capacity (Gb)	16	32	64	128	256